

January 1989

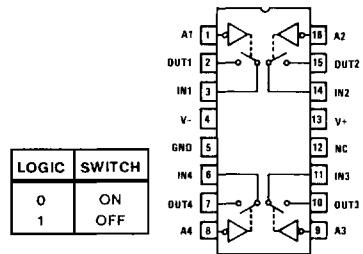
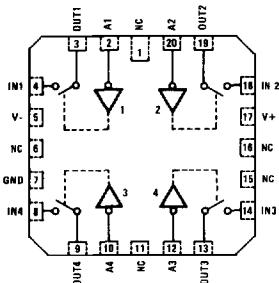
Features

- This Circuit is Processed in Accordance to Mil-Std-883 and is Fully Conformant Under the Provisions of Paragraph 1.2.1.
- Low "ON" Resistance 50Ω Max
- Wide Analog Signal Range ±15V
- Turn-On Time 50ns
- Analog Current Range (Continuous) 25mA
- TTL/CMOS Compatible
- No Latch-Up
- Pin Compatible with Standard HI-201

Applications

- High Speed Multiplexing
- High Frequency Analog Switching
- Sample and Hold Circuits
- Digital Filters
- Op Amp Gain Switching Networks
- Integrator Reset Circuits

Pinouts

**HI1-201HS/883 (CERAMIC DIP)
TOP VIEW**

**HI4-201HS/883 (CERAMIC LCC)
TOP VIEW**


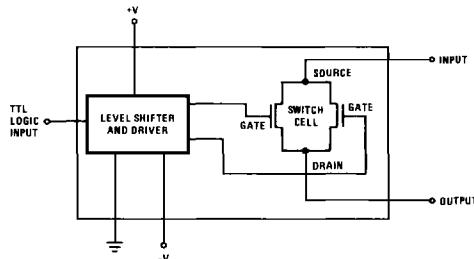
Description

HI-201HS/883 is a monolithic CMOS Analog Switch featuring very fast switching speeds and low ON resistance. This integrated circuit consists of four independently selectable SPST switches and is pin compatible with the industry standard HI-201 switch.

Fabricated using silicon-gate technology and the Harris dielectric isolation process, this TTL compatible device offers improved performance over previously available CMOS analog switches while eliminating the problem of latch-up associated with other fabricated processes. Featuring maximum switching times of 50ns, low ON resistance of 50Ω maximum, and a wide analog signal range, the HI-201HS/883 is designed for any military application where improved switching performance, particularly switching speed, is required. (A more detailed discussion on the design and application of the HI-201HS/883 can be found in Application Note 543).

The HI-201HS/883 is available in a 16 pin Ceramic DIP package and a 20 pin LCC package. The HI-201HS/883 is specified over the temperature range of -55°C to +125°C.

Functional Diagram



Specifications HI-201HS/883

Absolute Maximum Ratings

Voltage Between V+ and V- Terminals	36V
$\pm V_{SUPPLY}$ to Ground (V+, V-)	$\pm 18V$
Analog Input Voltage $+V_S$	$+V_{SUPPLY} + 2V$
$-V_S$	$-V_{SUPPLY} - 2V$
Digital Input Voltage $+V_A$	$+V_{SUPPLY} + 4V$
$-V_A$	$-V_{SUPPLY} - 4V$
Peak Current (S or D)	
(Pulse at 1ms, 10% Duty Cycle Max)	50mA
Continuous Current Any Terminal (Except S or D)	25mA
Junction Temperature	+175°C
Storage Temperature Range	-65°C to +150°C
Lead Temperature (Soldering 10 sec)	$\leq 275^\circ C$

Thermal Information

	θ_{ja}	θ_{jc}
Ceramic DIP Package	75°C/W	16°C/W
Ceramic LCC Package	76°C/W	19°C/W
Package Power Dissipation at $+75^\circ C$		
Ceramic DIP Package	1.0W	
Ceramic LCC Package	0.99W	
Package Power Dissipation Derating Factor Above $+75^\circ C$		
Ceramic DIP Package	13.36mW/°C	
Ceramic LCC Package	13.12mW/°C	
CAUTION: Absolute maximum ratings are limiting values, applied individually, beyond which the serviceability of the circuit may be impaired. Functional operability under any of these conditions is not necessarily implied.		

Recommended Operating Conditions

Operating Temperature Range	-55°C to +125°C	Logic Low Level (V_{AL})	0V to 0.8V
Operating Supply Voltage ($\pm V_{SUPPLY}$)	$\pm 15V$	Logic High Level (V_{AH})	3.0V to $+V_{SUPPLY}$
Analog Input Voltage (V_S)	$\pm V_{SUPPLY}$		

TABLE 1. D.C. ELECTRICAL PERFORMANCE CHARACTERISTICS

Device Tested at: $+V_{SUPPLY} = +15V$, $-V_{SUPPLY} = -15V$, GND = 0V, Unless Otherwise Specified

D.C. PARAMETERS	SYMBOL	CONDITIONS	GROUP A SUBGROUPS	TEMPERATURE	LIMITS		UNITS
					MIN	MAX	
Switch "ON" Resistance	R_{DS}	$V_{AL} = 0.8V$, $V_S = 10V$, $I_D = -1mA$ All Unused Channels $V_{AL} = 0.8V$	1	+25°C	-	50	Ω
			2, 3	-55°C to +125°C	-	75	Ω
	$I_{S(OFF)}$	$V_S = +14V$, $V_D = -14V$, $V_{AH} = 3.0V$ All Unused Channels $V_{AH} = 3.0V$, $V_D = +14V$, $V_S = -14V$	1	+25°C	-	50	nA
			2, 3	-55°C to +125°C	-100	100	nA
Source "OFF" Leakage Current	$I_{S(OFF)}$	$V_S = -14V$, $V_D = +14V$, $V_{AH} = 3.0V$ All Unused Channels $V_{AH} = 3.0V$, $V_D = -14V$, $V_S = +14V$	1	+25°C	-10	10	nA
			2, 3	-55°C to +125°C	-100	100	nA
	$I_{D(OFF)}$	$V_D = -14V$, $V_S = +14V$, $V_{AH} = 3.0V$ All Unused Channels $V_{AH} = 3.0V$, $V_D = +14V$, $V_S = -14V$	1	+25°C	-10	10	nA
			2, 3	-55°C to +125°C	-100	100	nA
Drain "OFF" Leakage Current	$I_{D(OFF)}$	$V_D = +14V$, $V_S = -14V$, $V_{AH} = 3.0V$ All Unused Channels $V_{AH} = 3.0V$, $V_D = -14V$, $V_S = +14V$	1	+25°C	-10	10	nA
			2, 3	-55°C to +125°C	-100	100	nA
	$I_{D(ON)}$	$V_D = V_S = +14V$, $V_{AL} = 0.8V$ All Unused Channels $V_{AL} = 0.8V$, $V_D = V_S = -14V$	1	+25°C	-10	10	nA
			2, 3	-55°C to +125°C	-100	100	nA
Channel "ON" Leakage Current	$I_{D(ON)}$	$V_D = V_S = -14V$, $V_{AL} = 0.8V$ All Unused Channels $V_{AL} = 0.8V$, $V_D = V_S = +14V$	1	+25°C	-10	10	nA
			2, 3	-55°C to +125°C	-100	100	nA
	I_{AL}	$V_{AL} = 0.8V$ All Unused Channels $V_{AH} = 4.0V$	1	+25°C	-	500	μA
			2, 3	-55°C to +125°C	-	500	μA
High Level Input Current	I_{AH}	$V_{AH} = 4.0V$ All Unused Channels $V_{AL} = 0.8V$	1	+25°C	-	40	μA
			2, 3	-55°C to +125°C	-	40	μA
Supply Current	$+I_{CC}$	All Channels $V_{AL} = 0.8V$	1, 2	+25°C, +125°C	-	10	mA
			3	-55°C	-	10	mA
	$-I_{CC}$	All Channels $V_{AH} = 3.0V$	1, 2	+25°C, +125°C	-	10	mA
			3	-55°C	-	10	mA
Supply Current	$-I_{CC}$	All Channels $V_{AL} = 0.8V$	1, 2	+25°C, +125°C	-	6	mA
			3	-55°C	-	6	mA
	$+I_{CC}$	All Channels $V_{AH} = 3.0V$	1, 2	+25°C, +125°C	-	6	mA
			3	-55°C	-	6	mA

CAUTION: These devices are sensitive to electrostatic discharge. Proper I.C. handling procedures should be followed.

TABLE 2. A.C. ELECTRICAL PERFORMANCE CHARACTERISTICS

Device Tested at: $+V_{SUPPLY} = +15V$, $-V_{SUPPLY} = -15V$, GND = 0V, Unless Otherwise Specified

PARAMETERS	SYMBOL	CONDITIONS	GROUP A SUBGROUPS	TEMPERATURE	LIMITS		UNITS
					MIN	MAX	
Turn "ON" Time	$t_{(ON)}$	$C_L = 35\text{pF}$, $R_L = 1\text{k}\Omega$ $V_{AH} = 3.0V$, $V_{AL} = 0.8V$	9	+25°C	-	50	ns
			10, 11	-55°C, +125°C	-	100	ns
Turn "OFF" Time	$t_{(OFF)}$	$C_L = 35\text{pF}$, $R_L = 1\text{k}\Omega$ $V_{AH} = 3.0V$, $V_{AL} = 0.8V$	9	+25°C	-	50	ns
			10, 11	-55°C, +125°C	-	100	ns

TABLE 3. ELECTRICAL PERFORMANCE CHARACTERISTICS (NOTE 1)

Device Characterized at: $+V_{SUPPLY} = +15V$, $-V_{SUPPLY} = -15V$, GND = 0V

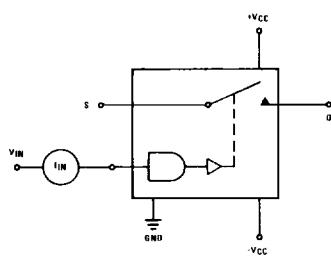
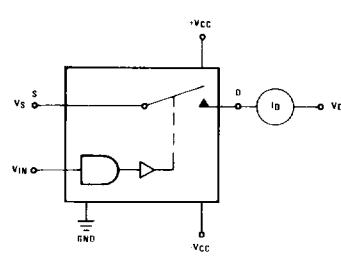
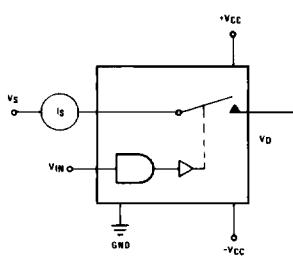
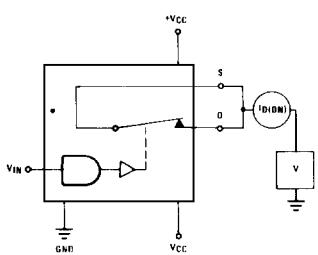
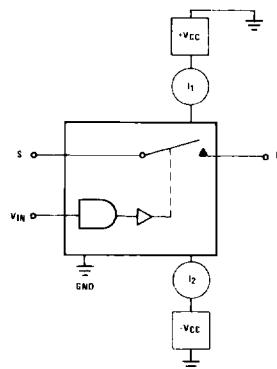
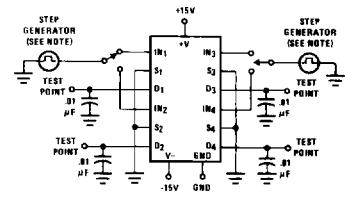
PARAMETERS	SYMBOL	CONDITIONS	NOTE	TEMPERATURE	LIMITS		UNITS
					MIN	MAX	
Address Capacitance	C_A	$f = 1\text{MHz}$, $V_{AL} = 0V$	1	+25°C	-	35	pF
Switch Input Capacitance	$C_{S(OFF)}$	$f = 1\text{MHz}$, $V_{AH} = 5V$ Measure Input to Ground	1	+25°C	-	20	pF
Switch Output Capacitance	$C_{D(OFF)}$	$f = 1\text{MHz}$, $V_{AH} = 5V$ Measure Output to Ground	1	+25°C	-	20	pF
	$C_{D(ON)}$	$f = 1\text{MHz}$, $V_{AL} = 0V$ Measure Output to Ground	1	+25°C	-	50	pF
Drain to Source Capacitance	C_{DS}	$f = 1\text{MHz}$, $V_{AH} = 5V$	1	+25°C	-	2.0	pF
Off Isolation	V_{ISO}	$f = 100\text{kHz}$, $V_A = 3.0$, $R_L = 1K$ $V_{GEN} = 1V_{p-p}$, $C_L = 10\text{pF}$	1	+25°C	50	-	dB
Crosstalk	V_{CT}	$f = 100\text{kHz}$, $V_A = 3.0$, $R_L = 1K$ $V_{GEN} = 1V_{p-p}$, $C_L = 10\text{pF}$	1	+25°C	50	-	dB
Charge Transfer Error	V_{CTE}	$R_L = 1K$, $C_L = 0.01\mu\text{F}$	1	+25°C	-	10	mV

NOTE 1. Parameters listed in Table 3 are controlled via design or process parameters and are not directly tested at final production. These parameters are lab characterized upon initial design release, or upon design changes. These parameters are guaranteed by characterization based upon data from multiple production runs which reflect lot to lot and within lot variation.

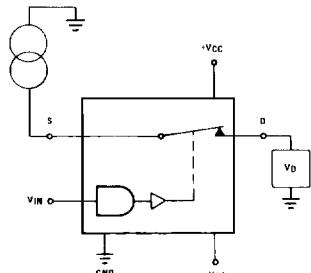
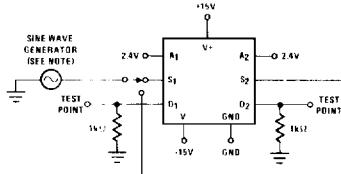
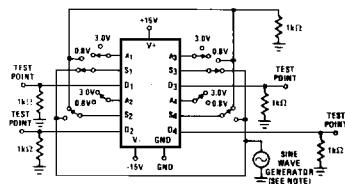
TABLE 4. ELECTRICAL TEST REQUIREMENTS

MIL-STD-883 TEST REQUIREMENTS	SUBGROUPS (SEE TABLES 1 & 2)
Interim Electrical Parameters (Pre Burn-in)	1
Final Electrical Test Parameters	1*, 2, 3, 9, 10, 11
Group A Test Requirements	1, 2, 3, 9, 10, 11
Groups C & D Endpoints	1

* PDA applies to Subgroup 1 only.

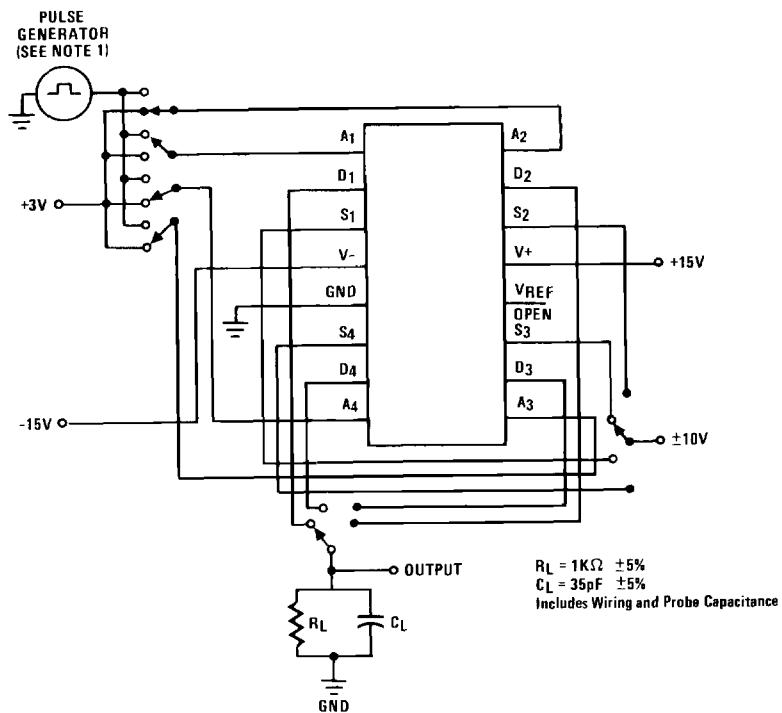
Test Circuits**INPUT LEAKAGE CURRENT****I_{D(OFF)}****I_{S(OFF)}****I_{D(ON)}****SUPPLY CURRENTS****CHARGE TRANSFER ERROR**

NOTE:
The pulse generator has the following characteristics: V_{GEN} = 0 to 3V, rise time \leq 20ns, fall time \leq 20ns, PRR = 100kHz.

R_{DS}**OFF CHANNEL ISOLATION****CROSSTALK
BETWEEN CHANNELS**

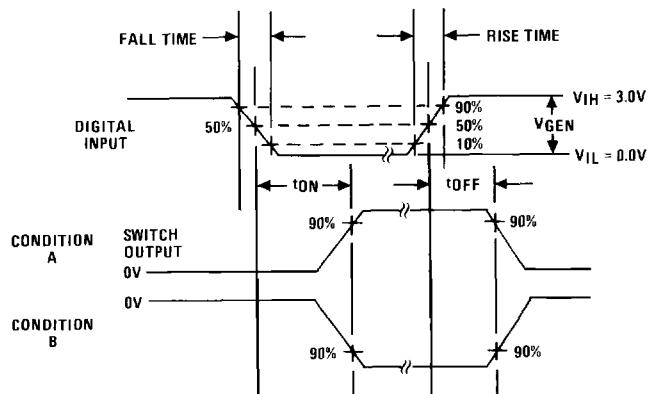
NOTE:
The pulse generator has the following characteristics: V_{GEN} = 1Vp-p, frequency = 100kHz.

See Test Tech Brief For Additional Information

Switching Waveforms

4

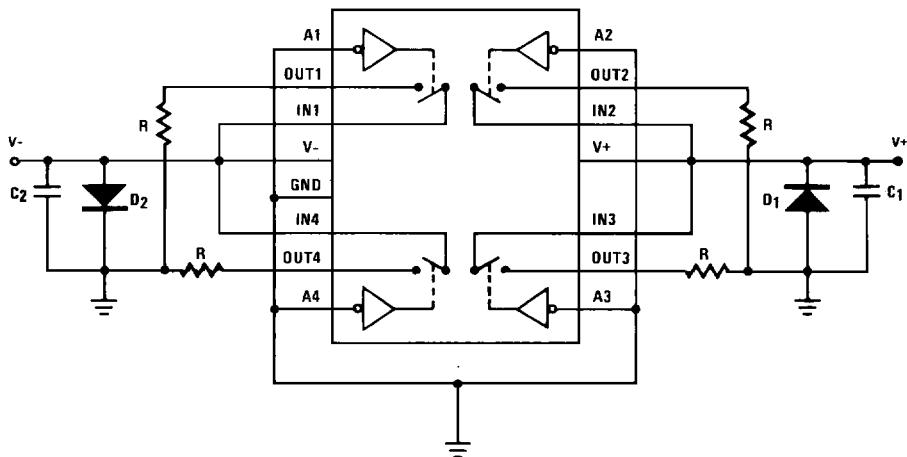
CMOS ANALOG SWITCHES



NOTE: Rise time and fall time ≤ 20ns

Burn-In Circuits

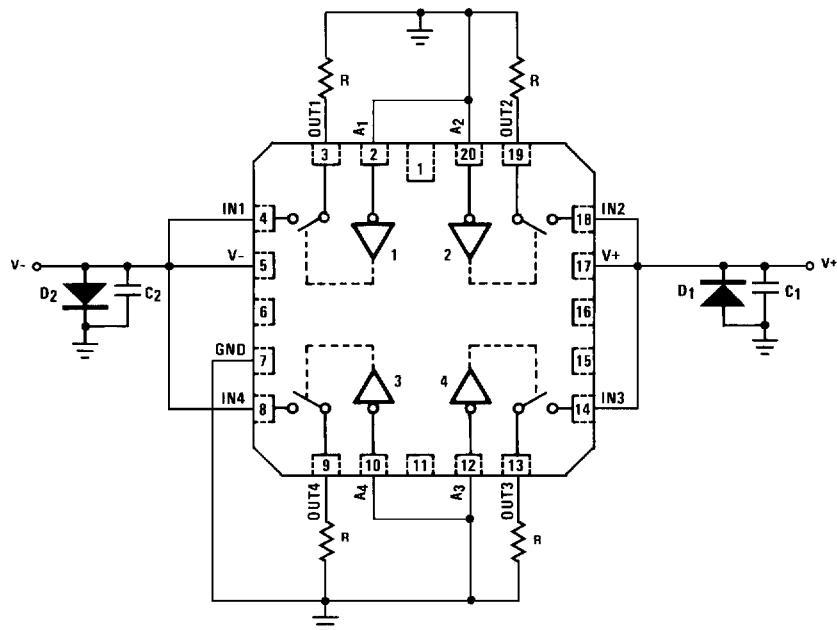
HI-201HS/883 CERAMIC DIP

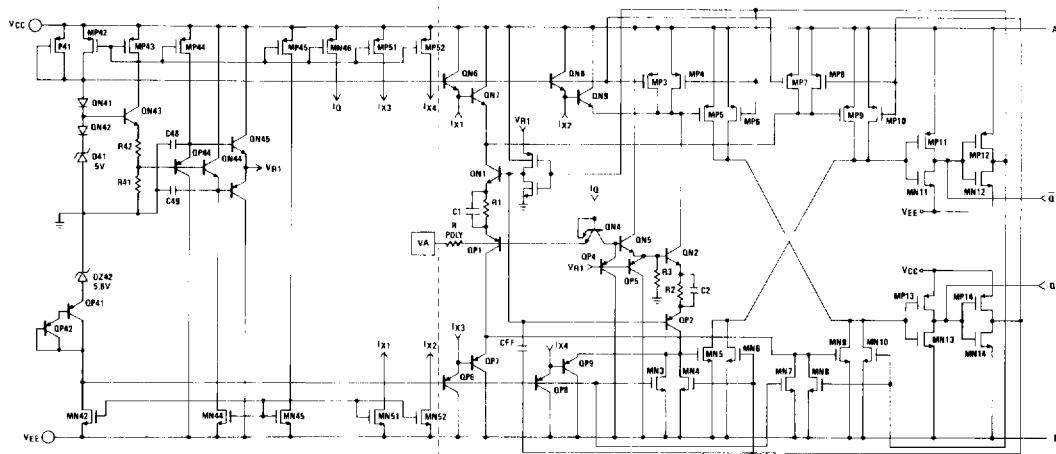


NOTES:

R = 10KΩ, 5%, 1/4 or 1/2W
 C₁ = C₂ = 0.1μF (one per row) or .01μF (one per socket)
 D₁ = D₂ = IN4002 or equivalent (one per board)
 |(V+) - (V-) | = 30V

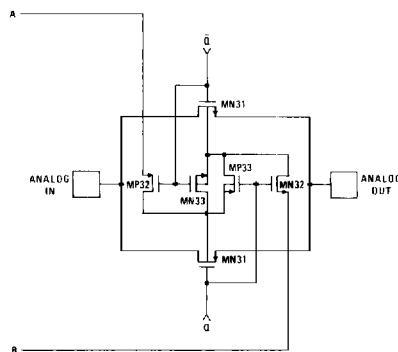
HI-201HS/883 CERAMIC LCC



Schematic Diagrams**REFERENCE/LEVEL SHIFTER**

4

CMOS ANALOG SWITCHES

SWITCH CELL

Die Characteristics**DIE DIMENSIONS:**

92 x 111 x 19 mils

METALLIZATION:

Type: Aluminum

Thickness: $16\text{k}\text{\AA} \pm 2\text{k}\text{\AA}$ **GLASSIVATION:**

Type: Nitride

Thickness: $7\text{k}\text{\AA} \pm 0.7\text{k}\text{\AA}$ **DIE ATTACH:**

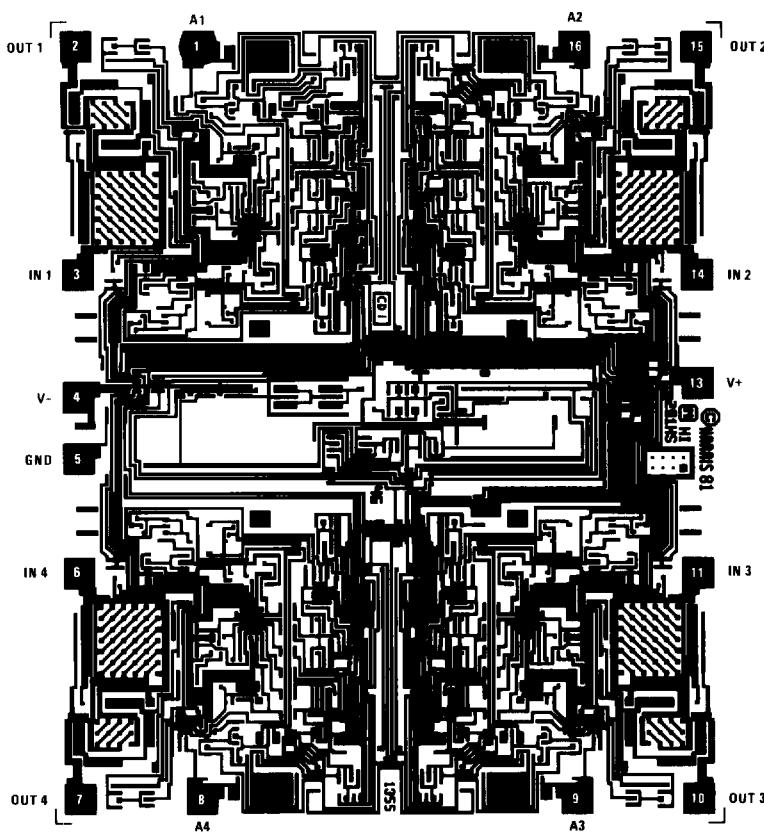
Material: Gold/Silicon Eutectic Alloy

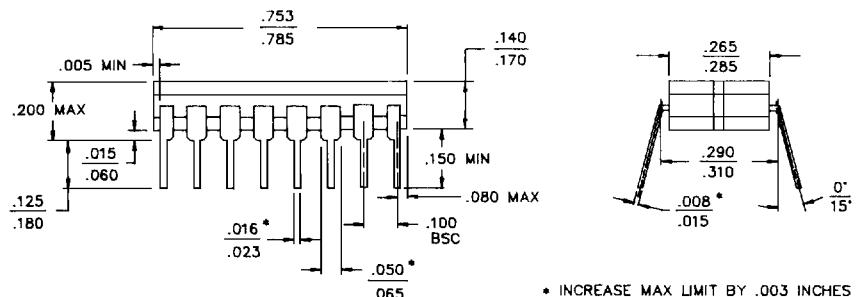
Temperature: Ceramic DIP — 460°C (Max)Ceramic LCC — 420°C (Max)**WORST CASE CURRENT DENSITY:** $4.5 \times 10^5 \text{A/cm}^2$ at 25mA

This device meets Glassivation Integrity Test requirement per Mil-Std-883 Method 2021 and Mil-M-38510 paragraph 3.5.5.4.

Metalization Mask Layout

HI-201HS/883



Packaging[†]**16 PIN CERAMIC DIP**

* INCREASE MAX LIMIT BY .003 INCHES
MEASURED AT CENTER OF FLAT FOR
SOLDER FINISH

LEAD MATERIAL: Type B

LEAD FINISH: Type A

PACKAGE MATERIAL: Ceramic, 90% Alumina

PACKAGE SEAL:

Material: Glass Frit

Temperature: 450°C ± 10°C

Method: Furnace Seal

INTERNAL LEAD WIRE:

Material: Aluminum

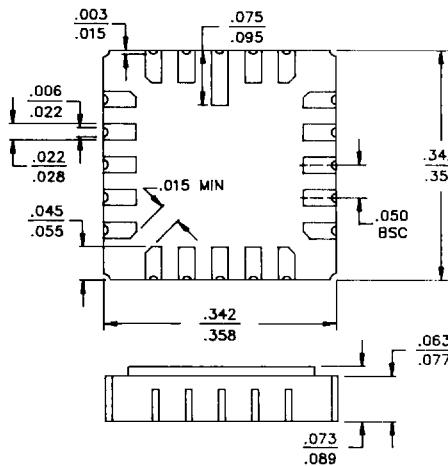
Diameter: 1.25 Mil

Bonding Method: Ultrasonic

COMPLIANT OUTLINE: 38510 D-2

4

CMOS ANALOG
SWITCHES

20 PAD CERAMIC LCC

PAD MATERIAL: Type C

PAD FINISH: Type A

FINISH DIMENSION: Type A

PACKAGE MATERIAL: Multilayer Ceramic, 90% Alumina

PACKAGE SEAL:

Material: Gold/Tin (80/20)

Temperature: 320°C ± 10°C

Method: Furnace Braze

INTERNAL LEAD WIRE:

Material: Aluminum

Diameter: 1.25 Mil

Bonding Method: Ultrasonic

COMPLIANT OUTLINE: 38510 C-2

NOTE: All Dimensions are Min to Max. Dimensions are in inches.

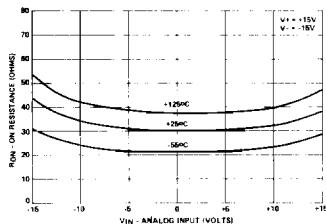
† Mil-M-38510 Compliant Materials, Finishes, and Dimensions.

DESIGN INFORMATION
**High Speed Quad SPST
CMOS Analog Switch**

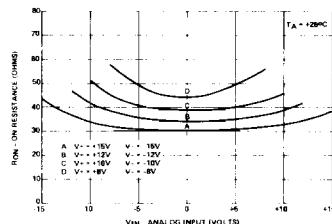
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Typical Performance Characteristics Unless Otherwise Specified: $T_A = +25^\circ\text{C}$, $V_{\text{SUPPLY}} = \pm 15\text{V}$
 $V_{\text{AH}} = 3.0\text{V}$, $V_{\text{AL}} = 0.8\text{V}$

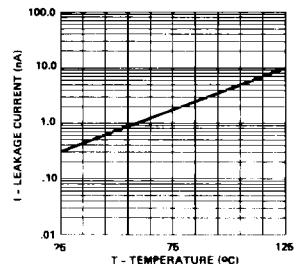
ON RESISTANCE vs. ANALOG SIGNAL LEVEL AND TEMPERATURE



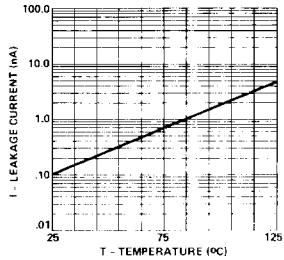
ON RESISTANCE vs. ANALOG SIGNAL LEVEL AND POWER SUPPLY VOLTAGE



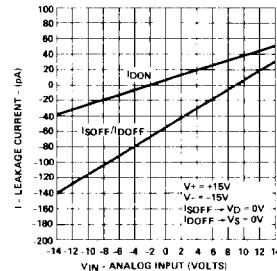
I_{S(OFF)} or I_{D(OFF)} vs. TEMPERATURE



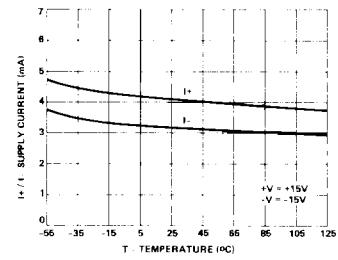
I_{D(ON)} vs. TEMPERATURE



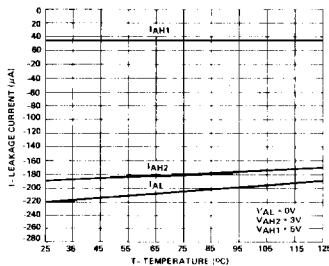
LEAKAGE CURRENT vs. ANALOG INPUT VOLTAGE



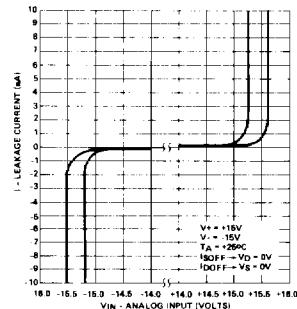
SUPPLY CURRENT vs. TEMPERATURE



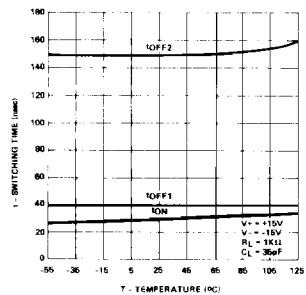
DIGITAL INPUT LEAKAGE CURRENT vs. TEMPERATURE



LEAKAGE CURRENT vs. ANALOG INPUT VOLTAGE ($V_{\text{IN}} \geq +14\text{V}$, $V_{\text{IN}} \geq -14\text{V}$)



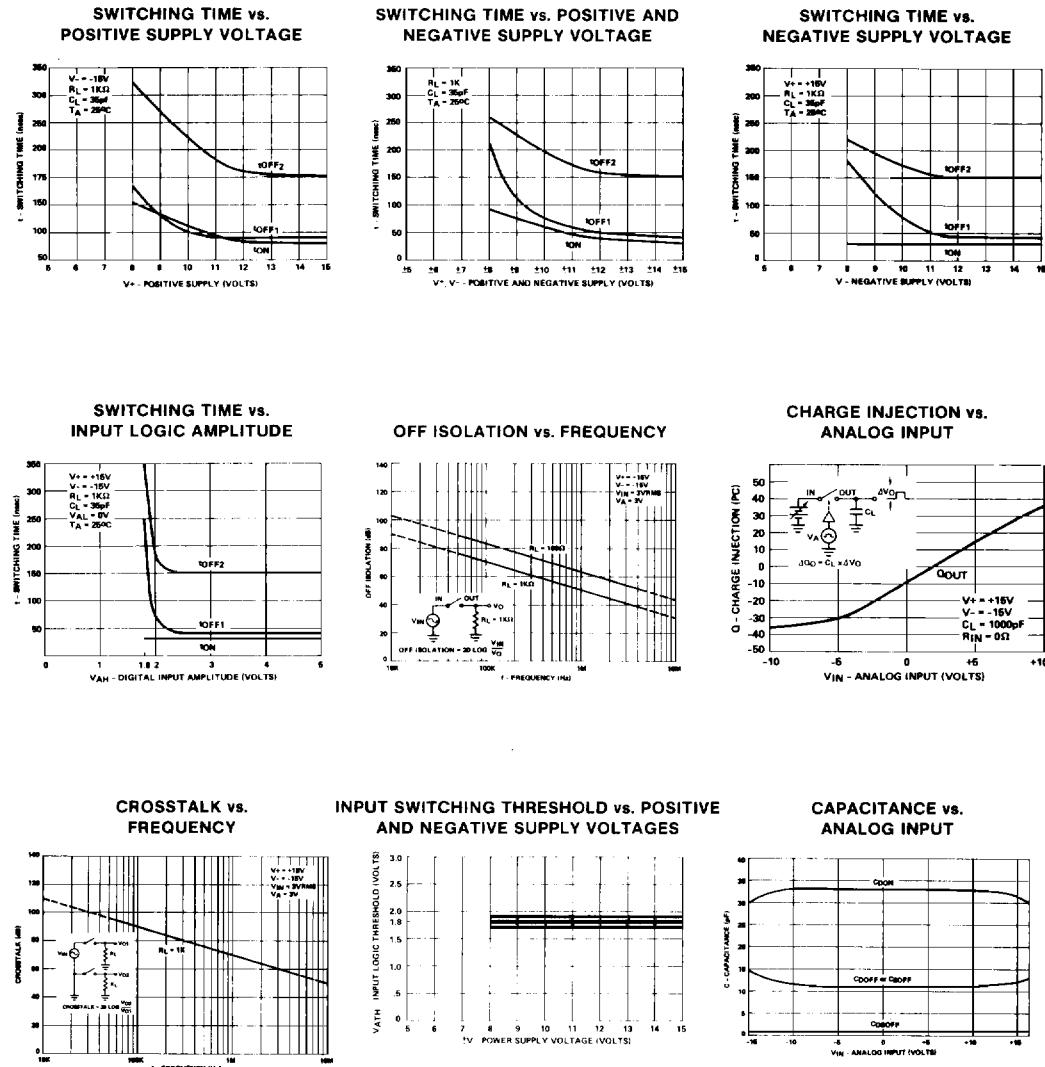
SWITCHING TIME vs. TEMPERATURE



DESIGN INFORMATION (Continued)

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Typical Performance Characteristics Unless Otherwise Specified: $T_A = +25^\circ\text{C}$, $V_{SUPPLY} = \pm 15\text{V}$
 $V_{AH} = 3.0\text{V}$, $V_{AL} = 0.8\text{V}$



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[NLX2G66DMUTCG](#) [NS5A4684SMNTAG](#) [732480R](#) [733995E](#) [425541DB](#) [425528R](#) [099044FB](#) [FSA221UMX](#) [MAX4888ETI+T](#)
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[NLAS4717EPFCT1G](#) [PI5A3167CCEX](#) [MAX4744ELB+T](#) [MAX4802ACXZ+](#) [SLAS3158MNR2G](#) [PI5A3157BC6EX](#) [PI5A392AQE](#)
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